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(54) **THIN FILM CAPACITOR (TFC)**
ARCHITECTURES FOR PACKAGE
SUBSTRATES

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(57) **ABSTRACT**

Embodiments disclosed herein include a package core. In an embodiment, the package core comprises a core substrate that includes glass. In an embodiment, a cavity is provided into the core substrate. In an embodiment, a capacitor is lining sidewalls of the cavity, and the capacitor comprises a first layer, a dielectric layer over the first layer, and a second layer over the dielectric layer.

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